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Formal drawings
J. White

PATENT RECEIVED
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MAR 26 2002
TC 2800 MAIL ROOM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hui et al.

Serial No.: 09/916,197

Filed: July 26, 2001

For: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Examiner: Unknown

Group Art Unit: 2841

Attorney Docket No.: 4712US (99-1054)



CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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Deidra Pfeil
Typed/printed name of person whose signature is contained above

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Attached please find the formal drawings for this application.

Respectfully submitted,

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Date: March 13, 2002
BGP/dlm